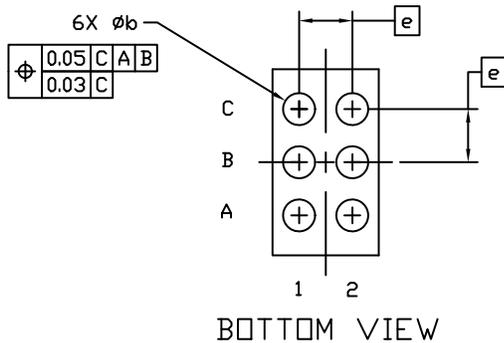
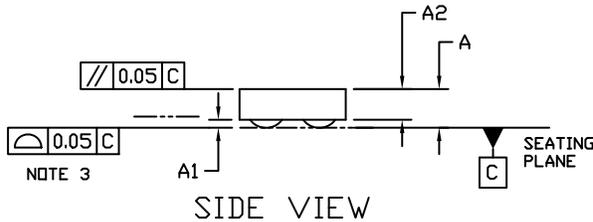
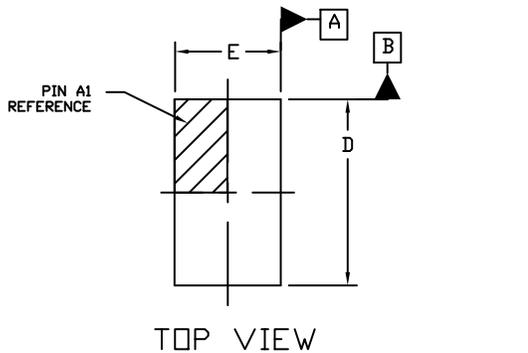


**WLCSP6 1.4x0.8x0.33**  
CASE 567XK  
ISSUE O

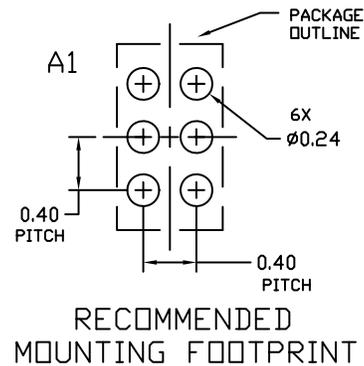
DATE 15 JAN 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.33
A1	0.040	0.060	0.080
A2	0.23 REF		
b	0.220	0.240	0.260
D	1.370	1.400	1.430
E	0.770	0.800	0.830
e	0.40 BSC		



**GENERIC MARKING DIAGRAM\***



XX = Specific Device Code  
M = Month Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>WLCSP6 1.4x0.8x0.33</b>	<b>PAGE 1 OF 1</b>

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